SS White Airbrasive Unit

Users may use this tool after receiving training from the facility staff. Log on in FOM to enable the instrument interlock, which will power up all necessary components, and log off when finished. It is not necessary to make reservations.

Get assistance from the facility staff in the following cases:

- 1) When turning on the unit, the pressure does not reach 75psi.
- 2) If sand ever comes out of the control unit and pressure drops below 65psi. Stop immediately to avoid eroding components.
- 3) If sand comes out of the nozzle when the pedal is not depressed. A rubber valve in the control unit may need to be replaced.
- 4) If no sand or air comes out of the nozzle when the pedal is depressed, remove the nozzle to see if it is clogged. If it is clear, the sand may need to be replenished.

It may be advisable wear a dust mask to avoid inhaling abrasive or abraded materials; users must provide their own masks as the facility is not authorized to do so. Roll up sleeves or wear long gloves to minimize sand on clothing.

Instructions for use:

- 1) Step on the foot lever of the gray dust collector, a few times to clear out the fan filter.
- 2) If necessary, switch on tool power strip. This will turn on air, dust collector, and lights.
- 3) Hold abrasive wand and use foot pedal to start flow of abrasive.
- 4) Adjust powder flow if desired; you may find lower flow rate number abrades faster than higher flow rates. Experimenting with nozzle-to-sample distance can be more effective. Do not adjust the air pressure. Various nozzle diameters are available. Use of other abrasives is possible; talk to facility staff if this is needed.

When finished:

- 1) Turn the power strip off.
- 2) Log off the instrument in FOM.
- 3) Clean up the desk and surrounding area. There is a vacuum in the corner if needed.

This power strip will turn on everything, AIR, DUST COLLECTOR, and LIGHTS

Full instructions on the wall.

Do not change the pressure of the unit. 75psi is the maximum system pressure.

If adding sand, make sure the o-ring on the upper cylinder has no sand on the surface.

Lowest flow rate may be most efficient.

Can etch through a silicon wafer in 2 seconds on '0', but it takes 5 seconds on '10'.